TO-252

Top View



TK9P65W-VB Datasheet

N-Channel 650V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.560			

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)



COMPLIANT

HALOGEN

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T_C	- 25 °C, un					
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	650	v	
Gate-source voltage			V _{GS}	± 30	V	
Continuous drain surrant $(T_{-} = 150 ^{\circ}\text{C})$	V _{GS} at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	۱ _D	8		
Continuous drain current (T _J = 150 °C)	VGS AL TO V	T _C = 100 °C		5	А	
Pulsed drain current ^a			I _{DM}	24		
Linear derating factor				1.7	W/°C	
Single pulse avalanche energy ^b			E _{AS}	330	mJ	
Maximum power dissipation			PD	180	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	$T_J = T_J$	125 °C	dV/dt	50	V/ns	
Reverse diode dV/dt ^d			av/dt	5.1	v/ns	
Soldering recommendations (peak temperature) ^c	nperature) ^c For 10 s			260	°C	

S

N-Channel MOSFET

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 Ω , I_{AS} = 4 A
- c. 1.6 mm from case
- d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C

TK9P65W-VB



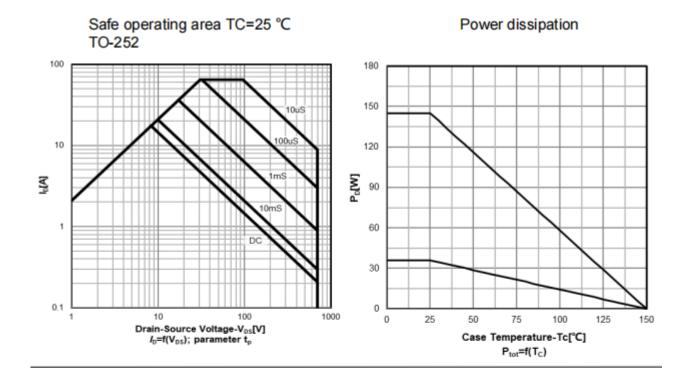
THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	- 62		20.044				
Maximum junction-to-case (drain)	R _{thJC}	- 0.85				°C/W		
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		650	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	$I_D = 1 \text{ mA}$	-	1.08	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$= V_{GS}, I_D =$	250 µA	2.0	-	4.0	V
Osta asuma laskana		$V_{GS} = \pm 20 V$		-	-	± 100	nA	
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
Zous and a valle as alusis summer		V _{DS} =	= 650 V, V _C	_{as} = 0 V	-	-	1	
Zero gate voltage drain current	IDSS	V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		√, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V I _D =2.5A		-	0.560	-	Ω	
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 8 A		-	8.7	-	S	
Dynamic	•	• •				•	•	
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	2300	-	pF	
Output capacitance	C _{oss}			-	51	-		
Reverse transfer capacitance	C _{rss}			-	12	-		
Effective output capacitance, energy related ^a	C _{o(er)}	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	52	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	205	-		
Total gate charge	Qg			-	25	-		
Gate-source charge	Q _{gs}	$V_{GS} = 10 V$	$V_{GS} = 10 \text{ V}$ $I_D = 8 \text{ A}, V_{DS} = 480 \text{ V}$		-	8	-	nC
Gate-drain charge	Q _{gd}				-	10	-	
Turn-on delay time	t _{d(on)}				-	12	24	
Rise time	t _r	Voo	= 480 V In	= 8 A	-	14	23	
Turn-off delay time	t _{d(off)}		V_{DD} = 480 V, I _D = 8 A, V _{GS} = 10 V, R _q = 9.1 Ω		-	61	110	ns
Fall time	t _f	5		-	16	-		
Gate input resistance	R _g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω	
Drain-Source Body Diode Characteristi	cs							
Continuous source-drain diode current	١ _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8		
Pulsed diode forward current	I _{SM}			-	-	24	A	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}				-	416	832	ns
Reverse recovery charge	Q _{rr}	T _J = 25 °C, $I_F = I_S = 8 A$, dl/dt = 100 A/µs, $V_R = 25 V$		-	6.4	12.8	μC	
Reverse recovery current	I _{RRM}			-	27	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

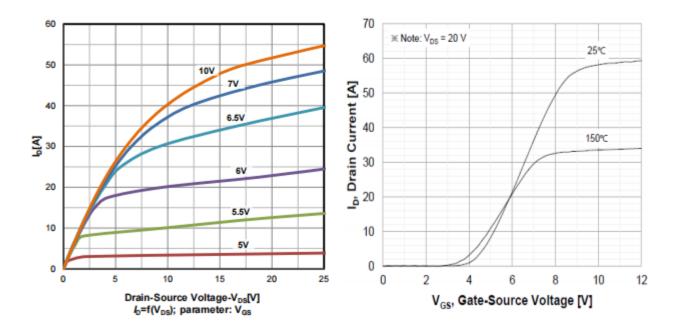


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Typ. output characteristics $T_i=25 \ ^{\circ}C$

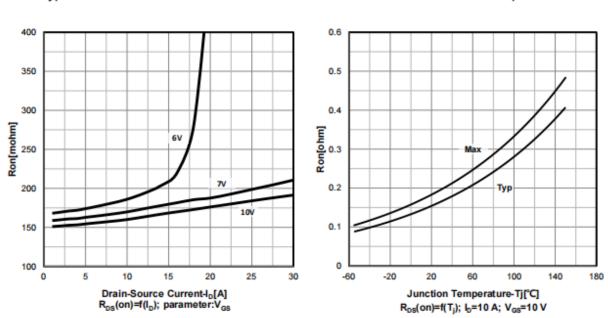
Transfer characteristics



服务热线:400-655-8788

TK9P65W-VB

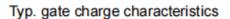


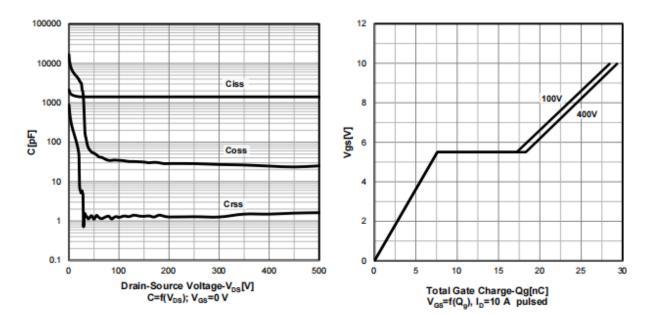


Typ. drain-source on-state resistance

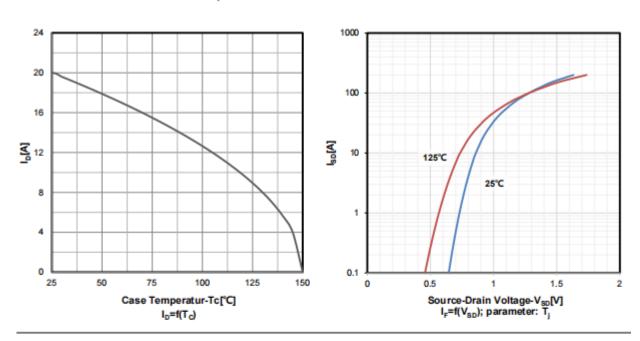
On-resistance vs temperature

Typ. capacitances







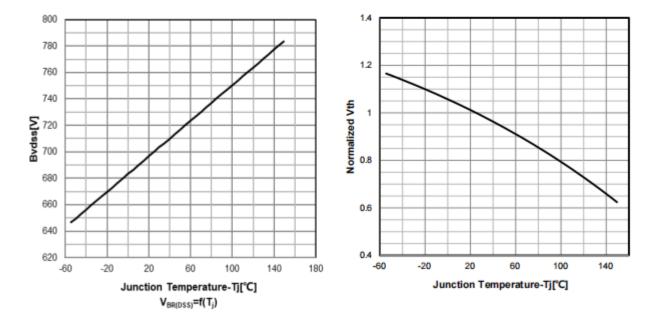


Drain current vs temperature

Forward characteristics of reverse diode

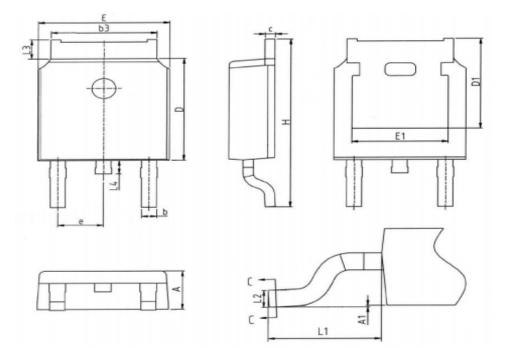
Drain-source breakdown voltage

Normalized VGS(th) characteristics





Package Outline : TO 252



COMMON DIMENSIONS

SYMBOL	UNIT(mm)				
SIMBOL	MIN	NOM	MAX		
A	2.20	2.30	2.40		
A1	0.00	-	0.127		
b	0.66	0.78	0.90		
b3	5.16	5.31	5.46		
с	0.43	0.53	0.63		
D	5.98	6.10	6.22		
D1	5.30REF				
E	6.40	6.60	6.75		
E1	4.63	-	-		
е	2.286BSC				
H	9.40	10.10	10.50		
L1	2.90REF				
L2	0.51BSC				
L3	0.88	1.08	1.28		
L4	0.50	0.80	1.00		



Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

Material Category Policy

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be oHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below :

IRFD120 JANTX2N5237 BUK455-60A/B MIC4420CM-TR VN1206L NDP4060 SI4482DY IPS70R2K0CEAKMA1 SQD23N06-31L-GE3 TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2 BSO203SP BSO211P IPA60R230P6 IPA60R460CE